

Cinterion® ELS31-V/ELS51-V

Hardware Interface Overview

Version: 00.502

Docld: ELS31-V_ELS51-V_HIO_v00.502



Document Name: Cinterion® ELS31-V/ELS51-V Hardware Interface Overview

Version: **00.502**

Date: 2015-12-07

Docld: ELS31-V ELS51-V HIO v00.502

Status: Confidential / Preliminary

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1 Introduction

This document¹ describes the hardware of the Cinterion[®] ELS31-V and ELS51-V modules for Verizon Network. It helps you quickly retrieve interface specifications, electrical and mechanical details and information on the requirements to be considered for integrating further components

The ELS31-V and ELS51-V modules include a baseband, a complete dual band RF frontend, memory and required circuitry to meet 3GPP E-UTRA (Long Term Evolution - LTE, Release 10 set of specifications) and Verizon Wireless LTE UE specifications.

The module variants differentiate a follows:

- ELS31-V provides LTE connectivity with IP Services
- ELS51-V adds a Linux execution environment available for customer applications

Note: Throughout the document ELS31-V refers to ELS31-V Release 2.

1.1 Key Features at a Glance

Feature	Implementation
General	
Frequency bands	LTE dualband: B4, B13
Output power	Class 3 (+23dBm +-2dB) for LTE AWS, LTE B4 Class 3 (+23dBm +-2dB) for LTE 700, LTE FDD B13
Power supply	3.3V to 4.5V
Operating temperature (board temperature)	Normal operation: -30°C to +80°C Extended operation: -40°C to +90°C
Physical	Dimensions: 27.6mm x 18.8mm x 2.2mm Weight: approx. 3g
RoHS	All hardware components fully compliant with EU RoHS Directive
LTE features	
3GPP Release 9	DL 10Mbps, UL 5Mbps LTE Cat. 1 data rates
SMS	Point-to-point MT and MO Text and PDU mode Storage in mobile equipment
Software	
AT commands	Hayes, 3GPP TS 27.007, TS 27.005, product specific
SIM Application Toolkit	SAT Release 99
Firmware update	Generic update from host application over ASC0 or USB modem OTA over ASC0 and over USB

^{1.} The document is effective only if listed in the appropriate Release Notes as part of the technical documentation delivered with your Gemalto M2M product.

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Feature	Implementation
Interfaces	
Module interface	Surface mount device with solderable connection pads (SMT application interface). Land grid array (LGA) technology ensures high solder joint reliability and allows the use of an optional module mounting socket.
	For more information on how to integrate SMT modules see also [4]. This application note comprises chapters on module mounting and application layout issues as well as on SMT application development equipment.
USB	USB 2.0 High Speed (480Mbit/s) device interface, Full Speed (12Mbit/s) compliant
2 serial interfaces	 ASC0: 8-wire modem interface with status and control lines, unbalanced, asynchronous Default baud rate: 115,200 baud Adjustable baud rates: 1,200 to 921,600, no autobauding support Supports RTS0/CTS0 hardware flow control. indication of incoming data/SMS on RING0 (can be used to wake up host from power down modes)
	ELS51-V only: ASC1 (shared with GPIO lines): 4-wire, unbalanced asynchronous interface Default baud rate: 115,200 baud Adjustable baud rates: 1,200bps to 921,600bps Supports RTS1/CTS1 hardware flow control
UICC interface	Supported SIM/USIM cards: 3V, 1.8V
Embedded UICC	Module is prepared for an embedded UICC
GPIO interface	20 pads of the application interface programmable as GPIO pads (17) or GPO pads (3): GP(I)Os can be configured as COUNTER, FST_SHDN, ASC0, ASC1, and SPI signal lines Programming is done via AT commands
I ² C interface	Supports I ² C serial interface
SPI interface	Supports SPI interface
SDIO	ELS51-V only: 4 wire interface.
HSIC	ELS51-V only: High Speed Interchip Communication interface.
ADC	Analog-to-Digital Converter with one unbalanced analog input.
Digitial audio interface	Hardware prepared for future use.
Antenna interface pads	50Ω LTE main antenna, 50Ω LTE diversity antenna

1.1 Key Features at a Glance

Feature	Implementation	
Power on/off, Reset		
Power on/off	Switch-on by hardware signal ON Switch-off by AT command Switch off by hardware signal GPIO4/FST_SHDN instead of AT command Automatic switch-off in case of critical temperature and voltage conditions	
Reset	Orderly shutdown and reset by AT command Emergency reset by hardware signal EMERG_RST	
Evaluation kit		
Evaluation module	ELS31-V / ELS51-V module soldered onto a dedicated PCB that can be connected to an adapter in order to be mounted onto the DSB75.	
DSB75	DSB75 Development Support Board designed to test and type approve Gemalto M2M modules and provide a sample configuration for application engineering. A special adapter is required to connect the ELS31-V / ELS51-V evaluation module to the DSB75.	

1.2 ELS31-V / ELS51-V System Overview

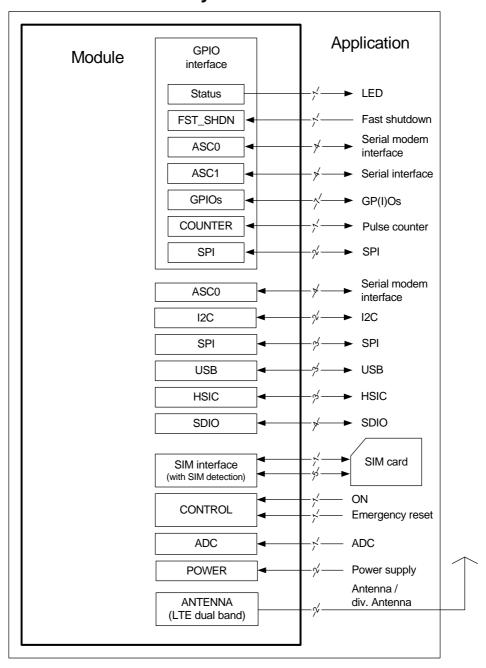


Figure 1: ELS31-V / ELS51-V system overview

2 Interface Characteristics

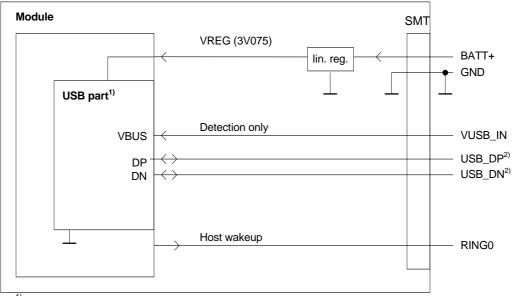
ELS31-V / ELS51-V is equipped with an SMT application interface that connects to the external application. The SMT application interface incorporates the various application interfaces as well as the RF antenna interfaces.

2.1 Application Interface

2.1.1 USB Interface

ELS31-V / ELS51-V supports a USB 2.0 High Speed (480Mbit/s) device interface that is Full Speed (12Mbit/s) compliant. The USB interface is primarily intended for use as command and data interface and for downloading firmware.

The V_{USB} line is used for cable detection only, this is to be supplied by the external device. The USB circuitry in the ELS31-V / ELS51-V is designed to meet the USB 2.0 specification for self-power.2.0".



¹⁾ It is recommended to add EMI suppression filter (see section 2.1.3.1)

Figure 2: USB circuit

To properly connect the module's USB interface to the external application, a USB 2.0 compatible connector and cable or hardware design is required. Furthermore, the USB modem driver distributed with ELS31-V / ELS51-V needs to be installed.

²⁾ If the USB interface is operated in High Speed mode (480MHz), it is recommended to take special care routing the data lines USB_DP and USB_DN. Application layout should in this case implement a differential impedance of 900hm for proper signal integrity.

^{1.} The specification is ready for download on http://www.usb.org/developers/docs/

2.1.2 Serial Interface ASC0

ELS31-V / ELS51-V offers an 8-wire unbalanced, asynchronous modem interface ASC0 conforming to ITU-T V.24 protocol DCE signalling. The electrical characteristics do not comply with ITU-T V.28. The significant levels are 0V (for low data bit or active state) and 1.8V (for high data bit or inactive state).

ELS31-V / ELS51-V is designed for use as a DCE. Based on the conventions for DCE-DTE connections it communicates with the customer application (DTE) using the following signals:

- Port TXD @ application sends data to the module's TXD0 signal line
- Port RXD @ application receives data from the module's RXD0 signal line

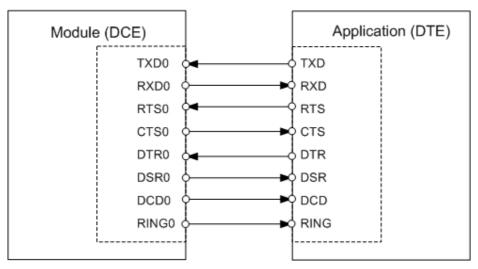


Figure 3: Serial interface ASC0

Features:

- Includes the data lines TXD0 and RXD0, the status lines RTS0 and CTS0 and, in addition, the modem control lines DTR0, DSR0, DCD0 and RING0.
- Configured for 8 data bits, no parity and 1 stop bit.
- ASC0 can be operated at fixed bit rates from 1200bps up to 921600bps.
- Supports RTS0/CTS0 hardware flow control. Communication is possible by using only RXD and TXD lines, if RTS0 is pulled low.
- Wake up from SLEEP mode by RTS0 activation (high to low transition).

2.1.3 Serial Interface ASC1 (ELS51-V Only)

ELS51-V provides a 4-wire unbalanced, asynchronous modem interface ASC1 conforming to ITU-T V.24 protocol DCE signalling. The electrical characteristics do not comply with ITU-T V.28. The significant levels are 0V (for low data bit or active state) and 1.8V (for high data bit or inactive state). With ELS31-V, ASC1 can only be used as data interface.

ELS51-V is designed for use as a DCE. Based on the conventions for DCE-DTE connections it communicates with the customer application (DTE) using the following signals:

- Port TXD @ application sends data to module's TXD1 signal line
- · Port RXD @ application receives data from the module's RXD1 signal line

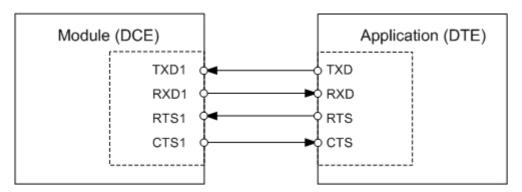


Figure 4: Serial interface ASC1

Features

- Includes only the data lines TXD1 and RXD1 plus RTS1 and CTS1 for hardware handshake.
- On ASC1 no RING line is available.
- Configured for 8 data bits, no parity and 1 or 2 stop bits.
- ASC1 can be operated at fixed bit rates from 1,200 bps to 921600 bps.
- Supports RTS1/CTS1 hardware flow control. Communication is possible by using only RXD and TXD lines, if RTS1 is pulled low.
- Wake up from SLEEP mode by RTS0 activation (high to low transition).

2.1.4 UICC/SIM/USIM Interface

ELS31-V / ELS51-V has an integrated UICC/SIM/USIM interface compatible with the 3GPP 31.102 and ETSI 102 221. This is wired to the host interface in order to be connected to an external SIM card holder. Five pads on the SMT application interface are reserved for the SIM interface.

The UICC/SIM/USIM interface supports 3V and 1.8V SIM cards.

The CCIN signal serves to detect whether a tray (with SIM card) is present in the card holder. Using the CCIN signal is mandatory for compliance with the GSM 11.11 recommendation if the mechanical design of the host application allows the user to remove the SIM card during operation. To take advantage of this feature, an appropriate SIM card detect switch is required on the card holder. For example, this is true for the model supplied by Molex, which has been tested to operate with ELS31-V / ELS51-V and is part of the Gemalto M2M reference equipment submitted for type approval. See Section 7.1 for Molex ordering numbers.

Table 1: Signals of the SIM interface (SMT application interface)

Signal	Description
GND	Separate ground connection for SIM card to improve EMC.
CCCLK	Chipcard clock
CCVCC	SIM supply voltage.
CCIO	Serial data line, input and output.
CCRST	Chipcard reset
CCIN	Input on the baseband processor for detecting a SIM card tray in the holder. If the SIM is removed during operation the SIM interface is shut down immediately to prevent destruction of the SIM. The CCIN signal is by default low and will change to high level if a SIM card is inserted. The CCIN signal is mandatory for applications that allow the user to remove the SIM card during operation. The CCIN signal is solely intended for use with a SIM card. It must not be used for any other purposes. Failure to comply with this requirement may invalidate the type approval of ELS31-V / ELS51-V.

Note: No guarantee can be given, nor any liability accepted, if loss of data is encountered after removing the SIM card during operation. Also, no guarantee can be given for properly initializing any SIM card that the user inserts after having removed the SIM card during operation. In this case, the application must restart ELS31-V / ELS51-V.

The figure below shows a circuit to connect an external SIM card holder.

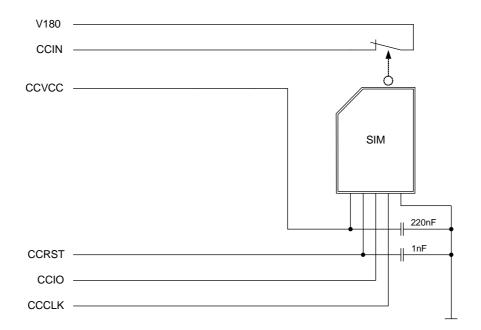


Figure 5: External UICC/SIM/USIM card holder circuit

The total cable length between the SMT application interface pads on ELS31-V / ELS51-V and the pads of the external SIM card holder must not exceed 100mm in order to meet the specifications of 3GPP TS 51.010-1 and to satisfy the requirements of EMC compliance.

To avoid possible cross-talk from the CCCLK signal to the CCIO signal be careful that both lines are not placed closely next to each other. A useful approach is using a GND line to shield the CCIO line from the CCCLK line.

2.1.5 GPIO Interface

ELS31-V / ELS51-V offers a GPIO interface with 17 GPIO and 3 GPO lines. The lines are shared with other interfaces or functions: Fast shutdown (see Section 2.1.11.2), status LED (see Section 2.1.11.1), a pulse counter (see Section 2.1.8), ASC0 (see Section 2.1.2), ASC1 (see Section 2.1.3), SPI (see Section 2.1.7), and HSIC (see Section 2.1.9).

The following table shows the configuration variants for the GPIO pads. All variants are mutually exclusive, i.e. a pad configured for instance as Status LED is locked for alternative usage.

Table 2: GPIO lines and possible alternative assignment

GPIO	Fast Shutdown	Status LED	Pulse Counter	ASC0	ASC1	SPI	HSIC
GPIO1				DTR0			
GPIO2				DCD0			
GPIO3				DSR0			
GPIO4	FST_SHDN						
GPO5		LED					
GPIO6							
GPIO7							
GPIO8			COUNTER				
GPIO16					RXD1		AP_WAKEUP
GPIO17					TXD1		HOST_ACTIVE
GPIO18					RTS1		CP_WAKEUP
GPIO19					CTS1		SUSPEND
GPIO20							
GPIO21							
GPIO22							
GPO23							
GPIO24				RING0			
GPIO25							
GPO26						SPI_CS1	
GPIO27						SPI_CS2	

After startup, the above mentioned alternative GPIO line assignments can be configured using AT commands (see [1]). The configuration is non-volatile and available after module restart.

Notes:

gemalto^x

GPO5, GPO23 and GPO26 are GPOs only.

2.1.6 I²C Interface

I²C is a serial, 8-bit oriented data transfer bus for bit rates up to 400kbps in Fast mode. It consists of two lines, the serial data line I2CDAT and the serial clock line I2CCLK. The module acts as a single master device, e.g. the clock I2CCLK is driven by the module. I2CDAT is a bi-directional line. Each device connected to the bus is software addressable by a unique 7-bit address, and simple master/slave relationships exist at all times. The module operates as master-transmitter or as master-receiver. The customer application transmits or receives data only on request of the module.

The I²C interface can be powered via the V180 line of ELS31-V / ELS51-V. If connected to the V180 line, the I²C interface will properly shut down when the module enters the Power Down mode.

Note: Good care should be taken when creating the PCB layout of the host application: The traces of I2CCLK and I2CDAT should be equal in length and as short as possible.

2.1.7 SPI Interface

Four ELS31-V / ELS51-V GPIO interface lines can be configured as Serial Peripheral Interface (SPI). The SPI is a synchronous serial interface for control and data transfer between ELS31-V / ELS51-V and the external application. Only one application can be connected to the SPI and the interface supports only master mode. The transmission rates are up to 6.5Mbit/s. The SPI interface comprises the two data lines MOSI and MISO, the clock line SPI_CLK a well as the chip select lines SPI_CS1 and SPI_CS2.

2.1.8 Pulse Counter

The GPIO8 line can be configured as pulse counter line COUNTER. The pulse counter interface can be used, for example, as a clock (for GPIOs see Section 2.1.5).

2.1.9 HSIC Interface (ELS51-V Only)

TBD

2.1.10 SDIO Interface (ELS51-V Only)

TBD

2.1.11 Control Signals

2.1.11.1 Status LED

The GPO5 interface line can be configured to drive a status LED that indicates different operating modes of the module (for GPIOs see Section 2.1.5). GPO and LED functionality are mutually exclusive.

2.1.11.2 Fast Shutdown

The GPIO4 interface line can be configured as fast shutdown signal line FST_SHDN. The configured FST_SHDN line is an active low control signal.

2.2 RF Antenna Interface

The RF interface has an impedance of 50Ω . ELS31-V /ELS51-V is capable of sustaining a total mismatch at the antenna line without any damage, even when transmitting at maximum RF power.

The external antenna must be matched properly to achieve best performance regarding radiated power, modulation accuracy and harmonic suppression. Antenna matching networks are not included on the ELS31-V / ELS51-V module and should be placed in the host application if the antenna does not have an impedance of 50Ω .

Regarding the return loss ELS31-V / ELS51-V provides the following values in the active band:

Table 3: Return loss in the active band

State of module	Return loss of module	Recommended return loss of application
Receive	≥ 8dB	≥ 12dB
Transmit	not applicable	≥ 12dB

2.2.1 Antenna Installation

The antenna is connected by soldering the antenna pads (RF_OUT, pad #59 and DIV_ANT, pad 56) its neighboring ground pads (GND, i.e., pads #55, #57, #58 and #60) directly to the application's PCB. The antenna pad is the antenna reference point (ARP) for ELS31-V / ELS51-V. All RF data specified throughout this document is related to the ARP.

The distance between the antenna RF pads and its neighboring GND pads has been optimized for best possible impedance. On the application PCB, special attention should be paid to these 3 pads, in order to prevent mismatch.

The wiring of the antenna connection line, starting from the antenna pad to the application antenna should result in a 50Ω line impedance. Line width and distance to the GND plane needs to be optimized with regard to the PCB's layer stack.

To prevent receiver desensitization due to interferences generated by fast transients like high speed clocks on the application PCB, it is recommended to realize the antenna connection line using embedded Stripline rather than Micro-Stripline technology.

For type approval purposes, the use of a 50Ω coaxial antenna connector (U.FL-R-SMT) might be necessary. In this case the U.FL-R-SMT connector should be placed as close as possible to ELS31-V / ELS51-V's antenna pad.

2.3 Sample Application

Figure 6 shows a typical example of how to integrate a ELS31-V / ELS51-V module with an application. Usage of the various host interfaces depends on the desired features of the application.

Because of the high RF field density inside the module, it cannot be guaranteed that no self interference might occur, depending on frequency and the applications grounding concept. The potential interferers may be minimized by placing small capacitors (47pF) at suspected lines (e.g. RXD0, VDDLP, and ON).

While developing SMT applications it is strongly recommended to provide test points for certain signals, i.e., lines to and from the module - for debug and/or test purposes. The SMT application should allow for an easy access to these signals. For details on how to implement test points see [4].

The EMC measures are best practice recommendations. In fact, an adequate EMC strategy for an individual application is very much determined by the overall layout and, especially, the position of components. For example, mounting the internal acoustic transducers directly on the PCB eliminates the need to use the ferrite beads shown in the sample schematic.

Note: ELS31-V / ELS51-V is not intended for use with cables longer than 3m.

Disclaimer

No warranty, either stated or implied, is provided on the sample schematic diagram shown in Figure 6 and the information detailed in this section. As functionality and compliance with national regulations depend to a great amount on the used electronic components and the individual application layout manufacturers are required to ensure adequate design and operating safeguards for their products using ELS31-V / ELS51-V modules.

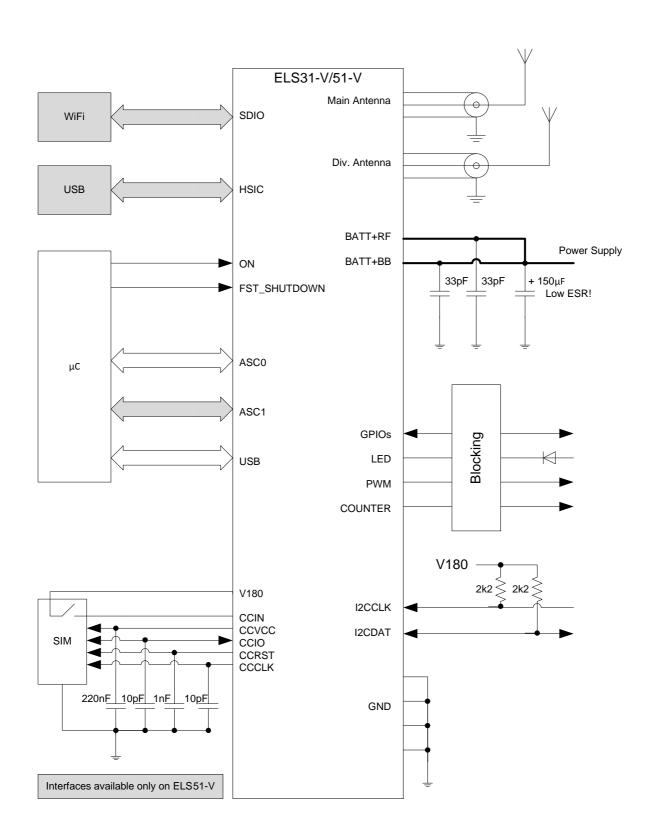


Figure 6: Schematic diagram of ELS31-V / ELS51-V sample application

3 Operating Characteristics

3.1 Operating Modes

The table below briefly summarizes the various operating modes referred to throughout the document.

Table 4: Overview of operating modes

Mode	Function		
Normal operation	LTE IDLE	No data transfer is in progress and the USB connection is suspended by host (or is not present) and no active communication via ASC0/ ASC1. In IDLE mode, the software can be active or in SLEEP state.	
	LTE DATA	LTE data transfer in progress. Power consumption depends on network settings and data transfer rate.	
Power Down	Normal shutdown after sending the power down command. Software is not active. Interfaces are not accessible. Operating voltage remains applied.		
Airplane mode	Airplane mode shuts down the radio part of the module, causes the module to log off from the LTE network and disables all AT commands whose execution requires a radio connection. Airplane mode can be controlled by AT command (see [1]). In Airplane mode, the software can be active or in SLEEP state.		

3.2 Power Supply

ELS31-V/ ELS51-V needs to be connected to a power supply at the SMT application interface - 2 BATT lines and GND. There are two separate voltage domains for BATT:

- BATT_BB with a line mainly for the baseband power supply.
- BATT_RF with a line for the RF power amplifier supply.

Please note that throughout the document BATT refers to both voltage domains and power supply lines - BATT_BB and BATT_RF.

The power supply of ELS31-V / ELS51-V has to be a single voltage source at BATT_BB and BATT_RF. It must be able to provide the current for all operation modes of the module.

All the key functions for supplying power to the device are handled by the power management section of the analog controller. This IC provides the following features:

- Stabilizes the supply voltages for the baseband using low drop linear voltage regulators and a DC-DC step down switching regulator.
- Switches the module's power voltages for the power-up and -down procedures.
- SIM switch to provide SIM power supply.

4 Mechanical Dimensions, Mounting and Packaging

4.1 Mechanical Dimensions of ELS31-V / ELS51-V

Figure 7 shows the top and bottom view of ELS31-V / ELS51-V and provides an overview of the board's mechanical dimensions. For further details see Figure 8.

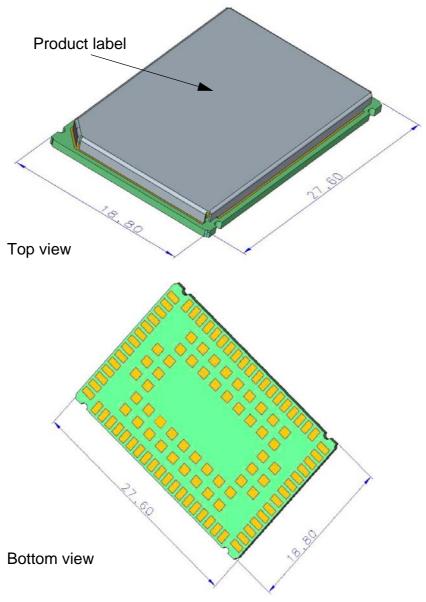


Figure 7: ELS31-V- top and bottom view

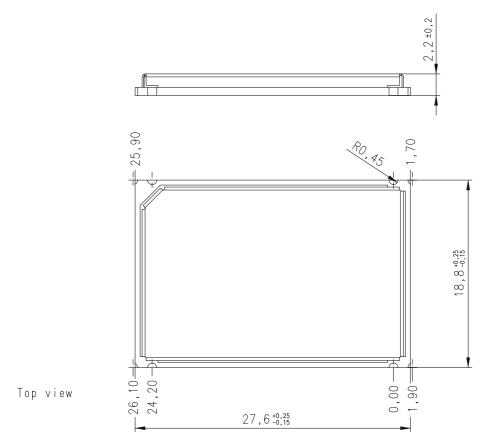


Figure 8: Dimensions of ELS31-V / ELS51-V (all dimensions in mm)

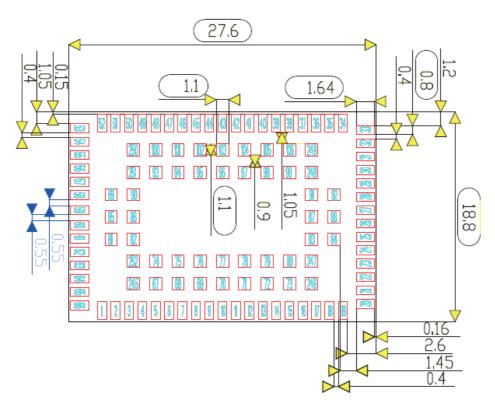


Figure 9: Dimensions of ELS31-V / ELS51-V (all dimensions in mm) - bottom view

5 Regulatory and Type Approval Information

5.1 Directives and Standards

ELS31-V / ELS51-V is designed to comply with the directives and standards listed below.

It is the responsibility of the application manufacturer to ensure compliance of the final product with all provisions of the applicable directives and standards as well as with the technical specifications provided in the "ELS31-V / ELS51-V Hardware Interface Description".

Table 5: Directives

2002/95/EC (RoHS 1) 2011/65/EC (RoHS 2)	Directive of the European Parliament and of the Council of 27 January 2003 (and revised on 8 June 2011) on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS)	RoH5 compliant
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Table 6: Standards of North American type approval

CFR Title 47	Code of Federal Regulations, Part 22 and Part 24 (Telecommunications, PCS); US Equipment Authorization FCC
OET Bulletin 65 (Edition 97-01)	Evaluating Compliance with FCC Guidelines for Human Exposure to Radiofrequency Electromagnetic Fields
UL 60 950-1	Product Safety Certification (Safety requirements)
California Leadfree Mandate	Covered by European RoHS requirements
RSS132 (Issue2) RSS133 (Issue5)	Canadian Standard

 Table 7: Standards of Verizon type approval

Verizon Wireless Unified Module Process for Compliance Testing and Approval, October 2014			
Verizon Wireless Device Requirements LTE 3GPP Band 13 Network Access, October 2014			
Verizon Wireless Device Requirements LTE 3GPP Band 4 Network Access, October 2014			
3GPP2 C.S0015-A v1.0 Short Message Service for spread spectrum systems			

Table 8: Standards of GCF type approval

3GPP TS 51.010-1	Digital cellular telecommunications system (Release 10); Mobile Station (MS) conformance specification;	
GCF-CC V3.58	Global Certification Forum - Certification Criteria	

Table 9: Requirements of quality

IEC 60068	Environmental testing		
DIN EN 60529	IP codes		

Table 10: Standards of the Ministry of Information Industry of the People's Republic of China

SJ/T 11363-2006	"Requirements for Concentration Limits for Certain Hazardous Substances in Electronic Information Products" (2006-06).
SJ/T 11364-2006	"Marking for Control of Pollution Caused by Electronic Information Products" (2006-06).
	According to the "Chinese Administration on the Control of Pollution caused by Electronic Information Products" (ACPEIP) the EPUP, i.e., Environmental Protection Use Period, of this product is 20 years as per the symbol shown here, unless otherwise marked. The EPUP is valid only as long as the product is operated within the operating limits described in the Gemalto M2M Hardware Interface Description. Please see Table 11 for an overview of toxic or hazardous substances or elements that might be contained in product parts in concentrations above the limits defined by SJ/T 11363-2006.

Table 11: Toxic or hazardous substances or elements with defined concentration limits

部件名称	有毒有害物质或元素 Hazardous substances					
Name of the part	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
金属部件 (Metal Parts)	0	0	0	0	0	0
电路模块 (Circuit Modules)	х	0	0	0	0	0
电缆及电缆组件 (Cables and Cable Assemblies)	0	0	0	0	0	0
塑料和聚合物部件 (Plastic and Polymeric parts)	0	0	0	0	0	0

0:

表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下。 Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X:

表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006标准规定的限量要求。 Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part *might exceed* the limit requirement in SJ/T11363-2006.

5.2 SAR requirements specific to portable mobiles

Mobile phones, PDAs or other portable transmitters and receivers incorporating a GSM module must be in accordance with the guidelines for human exposure to radio frequency energy. This requires the Specific Absorption Rate (SAR) of portable ELS31V / ELS51-V based applications to be evaluated and approved for compliance with national and/or international regulations.

Since the SAR value varies significantly with the individual product design manufacturers are advised to submit their product for approval if designed for portable use. For US markets the relevant directives are mentioned below. It is the responsibility of the manufacturer of the final product to verify whether or not further standards, recommendations or directives are in force outside these areas.

Products intended for sale on US markets

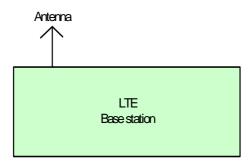
ES 59005/ANSI C95.1 Considerations for evaluation of human exposure to Electromagnetic Fields (EMFs) from Mobile Telecommunication Equipment (MTE) in the frequency range 30MHz - 6GHz

Please note that SAR requirements are specific only for portable devices and not for mobile devices as defined below:

- Portable device:
 - A portable device is defined as a transmitting device designed to be used so that the radiating structure(s) of the device is/are within 20 centimeters of the body of the user.
- Mobile device:
 - A mobile device is defined as a transmitting device designed to be used in other than fixed locations and to generally be used in such a way that a separation distance of at least 20 centimeters is normally maintained between the transmitter's radiating structure(s) and the body of the user or nearby persons. In this context, the term "fixed location" means that the device is physically secured at one location and is not able to be easily moved to another location.

5.3 Reference Equipment for Type Approval

The Gemalto M2M reference setup submitted to type approve ELS31-V / ELS51-V (including a special approval adapter for the DSB75) is shown in the following figure¹:



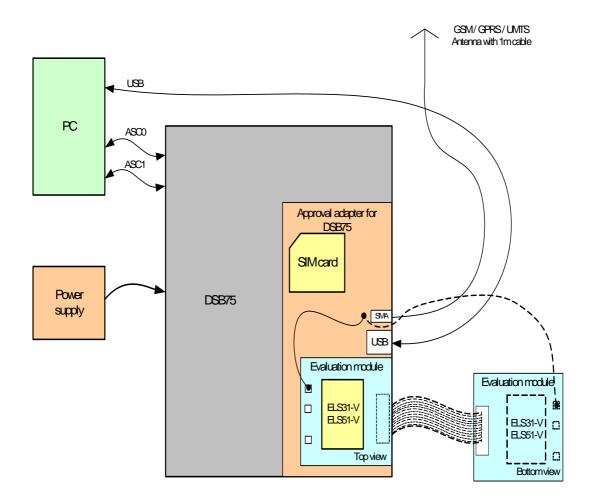


Figure 10: Reference equipment for Type Approval

For RF performance tests a mini-SMT/U.FL to SMA adapter with attached 6dB coaxial attenuator is chosen to connect the evaluation module directly to the GSM/UMTS test equipment instead of employing the SMA antenna connectors on the ELS31-V- / ELS51-V-DSB75 adapter as shown in Figure 10. The following products are recommended:

Hirose SMA-Jack/U.FL-Plug conversion adapter HRMJ-U.FLP(40)

⁽for details see see http://www.hirose-connectors.com/ or http://www.farnell.com/

Aeroflex Weinschel Fixed Coaxial Attenuator Model 3T/4T

⁽for details see http://www.aeroflex.com/ams/weinschel/pdfiles/wmod3&4T.pdf)

5.4 Compliance with FCC and IC Rules and Regulations

The Equipment Authorization Certification for the Gemalto M2M reference application described in Section 5.3 will be registered under the following identifiers:

ELS31-V:

FCC Identifier: QIPELS31-V (not yet granted)
Industry Canada Certification Number: 7830A-ELS31V (not yet granted)
Granted to Gemalto M2M GmbH

ELS51-V:

FCC Identifier: QIPELS51-V (not yet granted)
Industry Canada Certification Number: 7830A-ELS51V (not yet granted)
Granted to Gemalto M2M GmbH

Manufacturers of mobile or fixed devices incorporating ELS31-V / ELS51-V modules are authorized to use the FCC Grants and Industry Canada Certificates of the ELS31-V / ELS51-V modules for their own final products according to the conditions referenced in these documents. In this case, an FCC/ IC label of the module shall be visible from the outside, or the host device shall bear a second label stating "Contains FCC ID: QIPELS31-V" / "Contains FCC ID: QIPELS51-V", and accordingly "Contains IC: 7830A-ELS31V" / "Contains IC: 7830A-ELS51V". The integration is limited to fixed or mobile categorised host devices, where a separation distance between the antenna and any person of min. 20cm can be assured during normal operating conditions.

For mobile and fixed operation configurations the antenna gain, including cable loss, must not exceed the limits in the following Table 12 for FCC and IC.

Table 12: Antenna gain limits for FCC and IC

Operating band	FCC limit	IC limit	Unit
Maximum gain in lower operating bands with f< 1GHz (LTE Bd13)	10.4	7.4	dBi
Maximum gain in higher operating bands with f=1700MHz (LTE Bd4)	6.5	6.5	dBi

IMPORTANT:

Manufacturers of portable applications incorporating ELS31V / ELS51-V modules are required to have their final product certified and apply for their own FCC Grant and Industry Canada Certificate related to the specific portable mobile. This is mandatory to meet the SAR requirements for portable mobiles (see Section 5.2 for detail).

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules and with Industry Canada licence-exempt RSS standard(s). These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference

5.4 Compliance with FCC and IC Rules and Regulations

will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected
- Consult the dealer or an experienced radio/TV technician for help.

This Class B digital apparatus complies with Canadian ICES-003.

If Canadian approval is requested for devices incorporating ELS31V / ELS51-V modules the above note will have to be provided in the English and French language in the final user documentation. Manufacturers/OEM Integrators must ensure that the final user documentation does not contain any information on how to install or remove the module from the final product.

6 Document Information

6.1 Revision History

New document: "Cinterion® ELS31-V/ELS51-V Hardware Interface Overview" v00.502

Chapter	What is new
	Initial document setup.

6.2 Related Documents

- [1] ELS31-V / ELS51-V AT Command Set
- [2] ELS31-V / ELS51-V Release Note
- [3] Application Note 40: Thermal Solutions
- [4] Application Note 48: SMT Module Integration
- [5] Universal Serial Bus Specification Revision 2.0, April 27, 2000

6.3 Terms and Abbreviations

Abbreviation	Description
ADC	Analog-to-digital converter
AGC	Automatic Gain Control
ANSI	American National Standards Institute
ARFCN	Absolute Radio Frequency Channel Number
ARP	Antenna Reference Point
ASC0/ASC1	Asynchronous Controller. Abbreviations used for first and second serial interface of the modue
В	Thermistor Constant
BER	Bit Error Rate
BTS	Base Transceiver Station
CB or CBM	Cell Broadcast Message
CE	Conformité Européene (European Conformity)
CHAP	Challenge Handshake Authentication Protocol
CPU	Central Processing Unit
CS	Coding Scheme
CSD	Circuit Switched Data
CTS	Clear to Send
DAC	Digital-to-Analog Converter

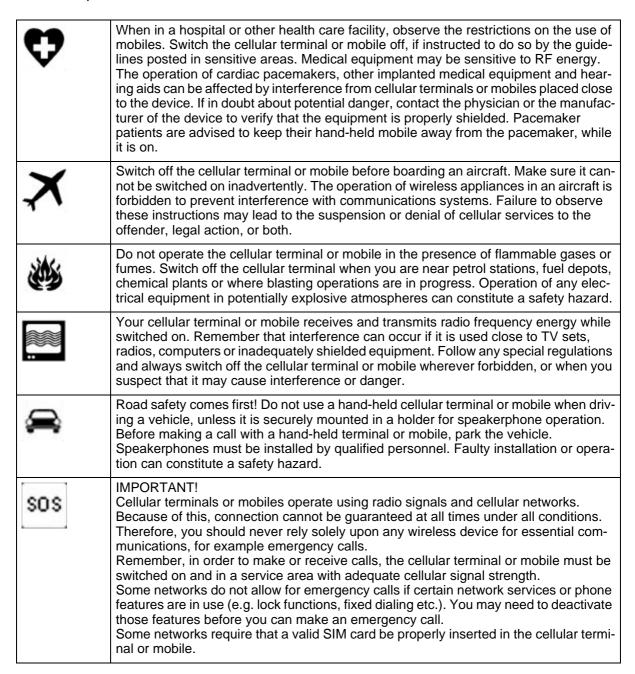
Abbreviation	Description		
DAI	Digital Audio Interface		
dBm0	Digital level, 3.14dBm0 corresponds to full scale, see ITU G.711, A-law		
DCE	Data Communication Equipment (typically modems, e.g. Gemalto M2M module)		
DCS 1800	Digital Cellular System, also referred to as PCN		
DRX	Discontinuous Reception		
DSB	Development Support Box		
DSP	Digital Signal Processor		
DSR	Data Set Ready		
DTE	Data Terminal Equipment (typically computer, terminal, printer or, for example, GSM application)		
DTR	Data Terminal Ready		
DTX	Discontinuous Transmission		
EFR	Enhanced Full Rate		
EGSM	Enhanced GSM		
EIRP	Equivalent Isotropic Radiated Power		
EMC	Electromagnetic Compatibility		
ERP	Effective Radiated Power		
ESD	Electrostatic Discharge		
ETS	European Telecommunication Standard		
FCC	Federal Communications Commission (U.S.)		
FDMA	Frequency Division Multiple Access		
FR	Full Rate		
GMSK	Gaussian Minimum Shift Keying		
GPIO	General Purpose Input/Output		
GPRS	General Packet Radio Service		
GSM	Global Standard for Mobile Communications		
HiZ	High Impedance		
HR	Half Rate		
I/O	Input/Output		
IC	Integrated Circuit		
IMEI	International Mobile Equipment Identity		
ISO	International Standards Organization		
ITU	International Telecommunications Union		
kbps	kbits per second		
LED	Light Emitting Diode		
Li-Ion/Li+	Lithium-Ion		
Li battery	Rechargeable Lithium Ion or Lithium Polymer battery		
LTE	Long Term Evolution		

Abbreviation	Description
Mbps	Mbits per second
MMI	Man Machine Interface
MO	Mobile Originated
MS	Mobile Station (GSM module), also referred to as TE
MSISDN	Mobile Station International ISDN number
MT	Mobile Terminated
NTC	Negative Temperature Coefficient
OEM	Original Equipment Manufacturer
PA	Power Amplifier
PAP	Password Authentication Protocol
PBCCH	Packet Switched Broadcast Control Channel
PCB	Printed Circuit Board
PCL	Power Control Level
PCM	Pulse Code Modulation
PCN	Personal Communications Network, also referred to as DCS 1800
PCS	Personal Communication System, also referred to as GSM 1900
PDU	Protocol Data Unit
PLL	Phase Locked Loop
PPP	Point-to-point protocol
PSK	Phase Shift Keying
PSU	Power Supply Unit
PWM	Pulse Width Modulation
R&TTE	Radio and Telecommunication Terminal Equipment
RAM	Random Access Memory
RF	Radio Frequency
RLS	Radio Link Stability
RMS	Root Mean Square (value)
RoHS	Restriction of the use of certain hazardous substances in electrical and electronic equipment.
ROM	Read-only Memory
RTC	Real Time Clock
RTS	Request to Send
Rx	Receive Direction
SAR	Specific Absorption Rate
SAW	Surface Accoustic Wave
SELV	Safety Extra Low Voltage
SIM	Subscriber Identification Module
SMD	Surface Mount Device

Abbreviation	Description
SMS	Short Message Service
SMT	Surface Mount Technology
SRAM	Static Random Access Memory
TA	Terminal adapter (e.g. GSM module)
TDMA	Time Division Multiple Access
TE	Terminal Equipment, also referred to as DTE
TLS	Transport Layer Security
Tx	Transmit Direction
UART	Universal asynchronous receiver-transmitter
URC	Unsolicited Result Code
USSD	Unstructured Supplementary Service Data
VSWR	Voltage Standing Wave Ratio

6.4 Safety Precaution Notes

The following safety precautions must be observed during all phases of the operation, usage, service or repair of any cellular terminal or mobile incorporating ELS31-V. Manufacturers of the cellular terminal are advised to convey the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. Failure to comply with these precautions violates safety standards of design, manufacture and intended use of the product. Gemalto M2M assumes no liability for customer's failure to comply with these precautions.



7 Appendix

7.1 List of Parts and Accessories

Table 13: List of parts and accessories

Description	Supplier	Ordering information
ELS31-V	Gemalto M2M	Standard module Gemalto M2M IMEI: Packaging unit (ordering) number: L30960-N4500-A200 Module label number: S30960-S4500-A200-1
ELS51-V	Gemalto M2M	Standard module Gemalto M2M IMEI: Packaging unit (ordering) number: L30960-N4530-A100 Module label number: S30960-S4530-A100-1
ELS31-V Evaluation Module	Gemalto M2M	Ordering number: L30960-N4501-A200
ELS51-V Evaluation Module	Gemalto M2M	Ordering number: L30960-N4531-A100
DSB75 Evaluation Kit	Gemalto M2M	Ordering number: L36880-N8811-A100
DSB Mini Compact Evaluation Board	Gemalto M2M	Ordering number: L30960-N0030-A100
Starter Kit B80	Gemalto M2M	Ordering Number L30960-N0040-A100
Multi-Adapter R1 for mounting ELS31-V/ELS51-V evaluation modules onto DSB75	Gemalto M2M	Ordering number: L30960-N0010-A100
Approval adapter for mounting ELS31-V/ELS51-V evaluation modules onto DSB75	Gemalto M2M	Ordering number: L30960-N2301-A100
SIM card holder incl. push button ejector and slide-in tray	Molex	Ordering numbers: 91228 91236 Sales contacts are listed in Table 14.

Table 14: Molex sales contacts (subject to change)

Molex For further information please click: http://www.molex.com	Molex Deutschland GmbH Otto-Hahn-Str. 1b 69190 Walldorf Germany Phone: +49-6227-3091-0 Fax: +49-6227-3091-8100 Email: mxgermany@molex.com	American Headquarters Lisle, Illinois 60532 U.S.A. Phone: +1-800-78MOLEX Fax: +1-630-969-1352
Molex China Distributors Beijing, Room 1311, Tower B, COFCO Plaza No. 8, Jian Guo Men Nei Street, 100005 Beijing P.R. China Phone: +86-10-6526-9628 Fax: +86-10-6526-9730	Molex Singapore Pte. Ltd. 110, International Road Jurong Town, Singapore 629174 Phone: +65-6-268-6868 Fax: +65-6-265-6044	Molex Japan Co. Ltd. 1-5-4 Fukami-Higashi, Yamato-City, Kanagawa, 242-8585 Japan Phone: +81-46-265-2325 Fax: +81-46-265-2365

About Gemalto

Gemalto (Euronext NL0000400653 GTO) is the world leader in digital security with 2014 annual revenues of €2.5 billion and blue-chip customers in over 180 countries. Our 14,000 employees operate out of 99 offices, 34 personalization and data centers, and 24 research and software development centers located in 46 countries.

We are at the heart of the rapidly evolving digital society. Billions of people worldwide increasingly want the freedom to communicate, travel, shop, bank, entertain and work - anytime, everywhere - in ways that are enjoyable and safe. Gemalto delivers on their expanding needs for personal mobile services, payment security, authenticated cloud access, identity and privacy protection, eHealthcare and eGovernment efficiency, convenient ticketing and dependable machine-to-machine (M2M) applications.

Gemalto develops secure embedded software and secure products which we design and personalize. Our platforms and services manage these secure products, the confidential data they contain and the trusted end-user services they enable. Our innovations enable our clients to offer trusted and convenient digital services to billions of individuals.

Gemalto thrives with the growing number of people using its solutions to interact with the digital and wireless world.

For more information please visit

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